

p-2.
1-12-05
Please
Enter

ABSTRACT OF THE DISCLOSURE

A deposited film forming apparatus ~~is provided~~
~~which~~ has a power applying electrode disposed above a
flat plate type base member grounded, in a vacuum
5 chamber, and a power source for supplying a power to
the power applying electrode, the deposited film
forming apparatus being constructed to supply the power
from the power source to the power applying electrode
so as to generate a plasma in a discharge space between
10 the power applying electrode and a substrate disposed
in opposition to the power applying electrode in the
vacuum chamber and serving as an electrode in a pair
with the power applying electrode, thereby decomposing
a source gas introduced into the vacuum chamber to form
15 a deposited film on the substrate, wherein the power
applying electrode is fixed to the base member with the
power applying electrode being isolated from the base
member. ~~A deposited film forming method using the~~
~~apparatus is also provided. This permits the power~~
20 ~~applying electrode to be fixed to the base member while~~
~~isolating the power applying electrode from the base~~
~~member, thereby preventing deformation of the power~~
~~applying electrode. As a consequence, occurrence of~~
~~plasma intrusion or abnormal discharge is prevented~~
25 ~~between the power applying electrode and the base~~
~~member.~~